



DGD0506A

HIGH FREQUENCY HALF-BRIDGE GATE DRIVER WITH PROGRAMMABLE DEADTIME

Description

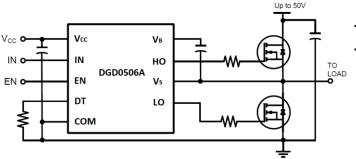
The DGD0506A is a high-frequency half-bridge gate driver capable of driving N-channel MOSFETs in a half-bridge configuration. The floating high-side driver is rated up to 50V.

The DGD0506A logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with MCUs. UVLO for high-side and low-side will protect a MOSFET with loss of supply. To protect MOSFETs, cross conduction prevention logic prevents the HO and LO outputs being on at the same time.

Fast and well-matched propagation delays allow a higher switching frequency, enabling a smaller, more compact power switching design using smaller associated components. The DGD0506A is offered in the W-DFN3030-10 (Type TH) & MSOP-10 packages and operates over an extended -40°C to +125°C temperature range.

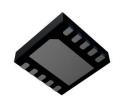
Applications

- DC-DC Converters
- Motor Controls
- Battery Powered Hand Tools
- eCig Devices
- Class D Power Amplifiers



Typical Configuration





Top View

Bottom View

W-DFN3030-10 (Type TH)

- Features
- 50V Floating High-Side Driver
- Drives Two N-Channel MOSFETs in a Half-Bridge Configuration
- 1.5A Source / 2.0A Sink Output Current Capability
- Internal Bootstrap Diode Included
- Undervoltage Lockout for High-Side and Low-Side Drivers
- Programmable Deadtime to Protect MOSFETs
- Logic Input (IN and EN) 3.3V Capability
- Ultra Low Standby Currents (<1µA)
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: W-DFN3030-10 (Type TH)
- Case material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Finish Solderable per MIL-STD-202, Method 208 (€3)
- Weight: 0.017 grams (Approximate)

Mechanical Data

- Case: MSOP-10
- Case material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 (€3)
- Weight: 0.0286 grams (Approximate)



Top View

MSOP10

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Notes:

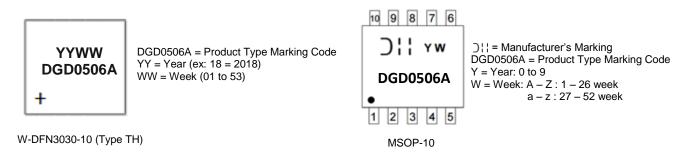


Ordering Information (Note 4)

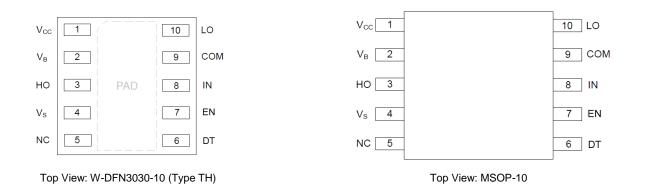
Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD0506AFN-7	DGD0506A	7	8	3,000
DGD0506AM10-13	DGD0506A	13	12	2,500

Note: 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Pin Diagrams

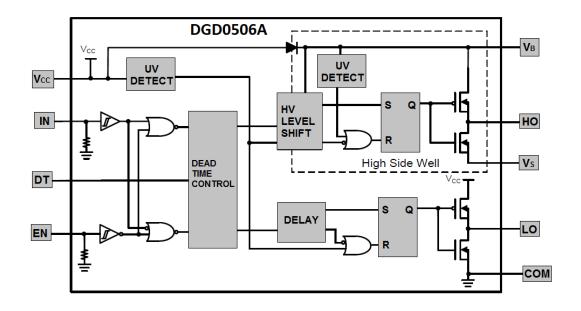


Pin Descriptions

Pin Number	Pin Name	Function
1	V _{CC}	Low-Side and Logic Supply
2	VB	High-Side Floating Supply
3	HO	High-Side Gate Drive Output
4	Vs	High-Side Floating Supply Return
5	NC	No Connect (No Internal Connection)
6	DT	Deadtime Control
7	EN	Logic Input Enable, a Logic Low turns off Gate Driver
8	IN	Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO
9	COM	Low-Side and Logic Return
10	LO	Low-Side Gate Drive Output
PAD	Substrate	Connect to COM on PCB



Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Positive Supply Voltage	VB	-0.3 to +60	V
High-Side Floating Negative Supply Voltage	Vs	V _B -14 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S /dt	50	V/ns
Logic and Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +14	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (IN and EN)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics – W-DFN3030-10 (Type TH) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	64	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	42	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	TL	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Thermal Characteristics – MSOP-10 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 6)	PD	0.75	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{0JA}	166	°C/W
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	32	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	TL	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 6. When mounted on a standard JEDEC 2-layer FR-4 board with minimum recommended pad layout.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply	VB	V _S + 8	V _S + 14	V
High-Side Floating Supply Offset Voltage	Vs	(Note 7)	50 (Note 8)	V
High-Side Floating Output Voltage	V _{HO}	Vs	VB	V
Logic and Low Side Fixed Supply Voltage	Vcc	8	14	V
Low-Side Output Voltage	V _{LO}	0	V _{CC}	V
Logic Input Voltage (IN and EN)	V _{IN}	0	5	V
Ambient Temperature	TA	-40	+125	°C

Notes: 7. Logic operation for V_S of -5V to +50V.

8. Provided VB doesn't exceed absolute maximum rating of 60V.



DC Electrical Characteristics ($V_{CC} = V_{BS} = 12V$, COM = $V_S = 0V$, $@T_A = +25^{\circ}C$, unless otherwise specified.) (Note 9)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Logic "1" Input Voltage	VIH	2.4	-	-	V	-
Logic "0" Input Voltage	VIL	-	-	0.8	V	-
Enable Logic "1" Input Voltage	V _{ENIH}	1.5	-	_	V	-
Enable Logic "0" Input Voltage	V _{ENIL}	-	-	0.7	V	-
Input Voltage Hysteresis	VINHYS	-	0.6	-	V	-
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	-	0.45	0.6	V	I _{O+} = 100mA
Low Level Output Voltage, V _O	V _{OL}	-	0.15	0.22	V	I _{O-} = 100mA
Offset Supply Leakage Current	I _{LK}	-	10	50	μA	$V_B = V_S = 60V$
V _{CC} Shutdown Supply Current	ICCSD	-	0	1	μA	$V_{IN} = 0V$ or 5V, $V_{EN} = 0V$
V _{CC} Quiescent Supply Current	Iccq	-	0.28	0.5	mA	$V_{IN} = 0V \text{ or } 5V,$ $R_{DT} = 100k\Omega$
V _{CC} Operating Supply Current	I _{CCOP}	-	7.6	-	mA	$fs = 500 kHz, C_L = 1000 pF$
V _{BS} Quiescent Supply Current	I _{BSQ}	-	32	100	μA	$V_{IN} = 0V \text{ or } 5V$
V _{BS} Operating Supply Current	IBSOP	-	7.6	-	mA	$fs = 500 kHz, C_L = 1000 pF$
Logic "1" Input Bias Current	I _{IN+}	-	25	60	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	I _{IN-}	-	0	1	μA	$V_{IN} = 0V$
V _{BS} Supply Undervoltage Positive Going Threshold	V _{BSUV+}	6.0	7.0	8.0	V	-
V _{BS} Supply Undervoltage Negative Going Threshold	V _{BSUV-}	5.6	6.6	7.6	V	-
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	6.0	7.0	8.0	V	-
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV} -	5.6	6.6	7.6	V	-
Output High Short-Circuit Pulsed Current	I _{O+}	0.9	1.5	-	A	V _O = 0V, PW ≤ 10µs
Output Low Short-Circuit Pulsed Current	I _{O-}	1.5	2.0	_	A	V _O = 15V, PW ≤ 10µs
Forward Voltage of Bootstrap Diode	V _{F1}	-	0.67	_	V	I _F = 100µA
Forward Voltage of Bootstrap Diode	V _{F2}	-	1.7	_	V	$I_F = 100 \text{mA}$

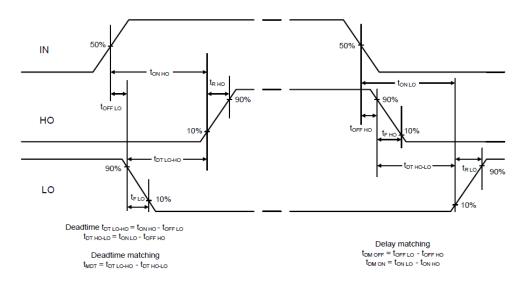
Note: 9. The V_{IN} and I_{IN} parameters are applicable to the two logic pins: IN and EN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics ($V_{CC} = V_{BS} = 12V$, COM = $V_S = 0V$, $C_L = 1000pF$, $@T_A = +25^{\circ}C$, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Turn-on Propagation Delay, HO & LO		65	96	125	ns	$R_{DT} = 10k\Omega$
Tum-on Propagation Delay, HO & LO	ton	350	463	580	ns	R _{DT} = 100kΩ
Turn-off Propagation Delay, HO & LO	tOFF	-	22	56	ns	-
Turn-on Rise Time	t _R	-	17	35	ns	-
Turn-off Fall Time	t _F	-	12	25	ns	-
Delay Matching	t _{DM}	-	-	50	ns	-
		40	70	100	ns	R _{DT} = 10kΩ
Deadtime: t _{DT LO-HO} & t _{DT HO-LO}	t _{DT}	300	430	560	ns	R _{DT} = 100kΩ
Deadtime Matching	t _{MDT}	-	-	50	ns	R _{DT} = 100kΩ



Timing Waveforms





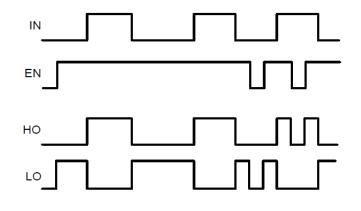


Figure 2. Input / Output Timing Diagram



Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

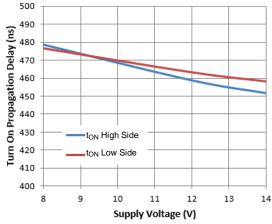


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

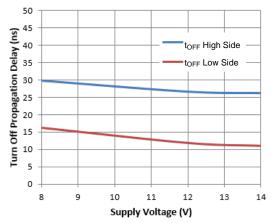


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

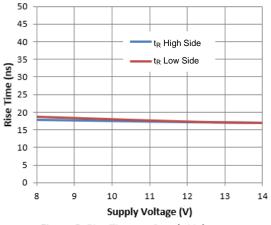


Figure 8. Rise Time vs. Supply Voltage

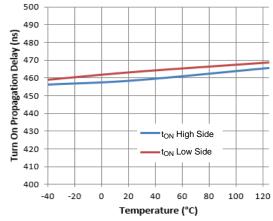


Figure 5. Turn-on Propagation Delay vs. Temperature

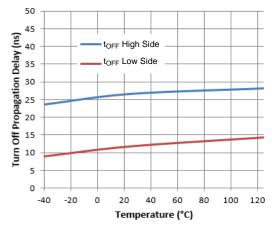


Figure 7. Turn-off Propagation Delay vs. Temperature

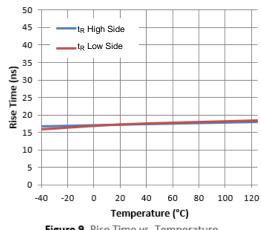
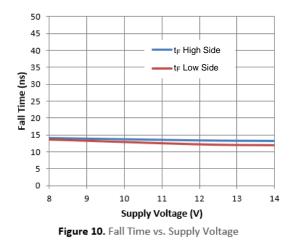


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Cont.)



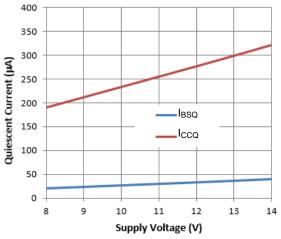


Figure 12. Quiescent Current vs. Supply Voltage

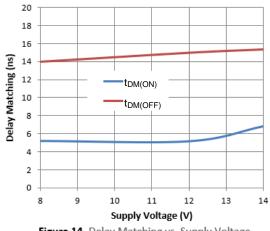
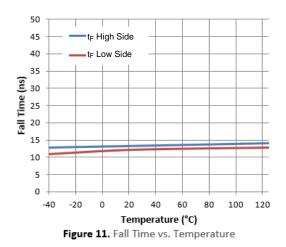
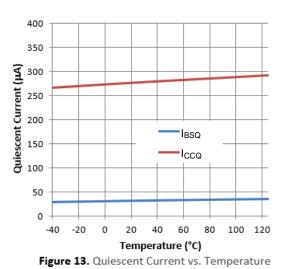


Figure 14. Delay Matching vs. Supply Voltage





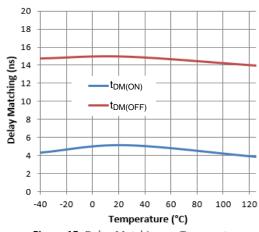


Figure 15. Delay Matching vs. Temperature



Typical Performance Characteristics (Cont.)

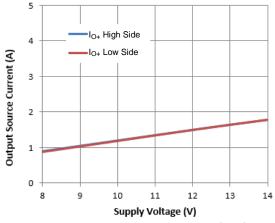


Figure 16. Output Source Current vs. Supply Voltage

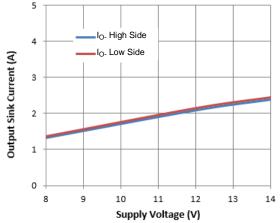


Figure 18. Output Sink Current vs. Supply Voltage

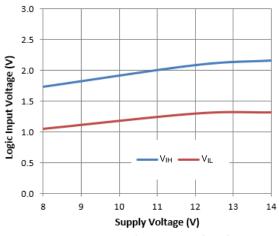


Fig 20. Logic Input Voltage vs. Supply Voltage

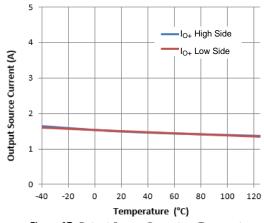
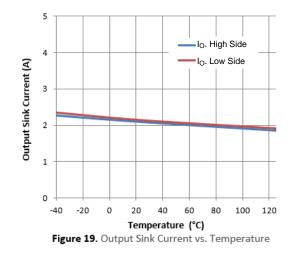
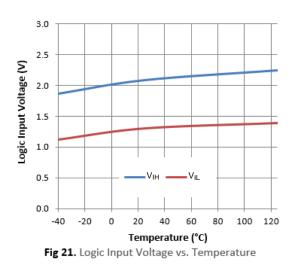


Figure 17. Output Source Current vs. Temperature







Typical Performance Characteristics (Cont.)

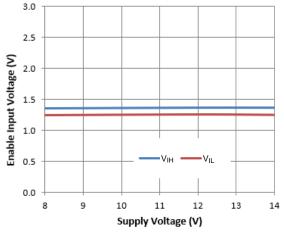


Fig 22. Enable Input Voltage vs. Supply Voltage

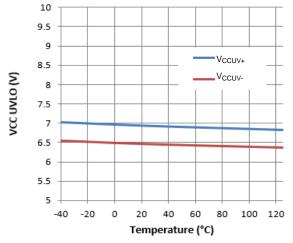


Figure 24. VCC UVLO vs. Temperature

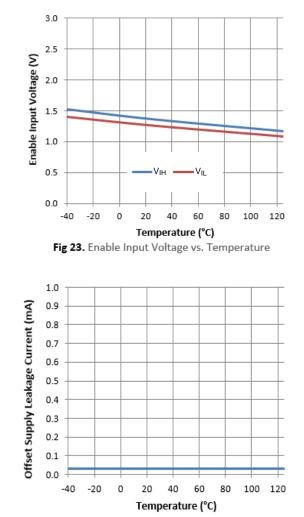
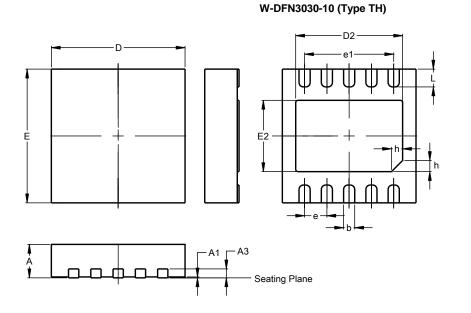


Figure 25. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

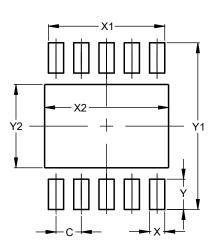
Please see http://www.diodes.com/package-outlines.html for the latest version.



W-DFN3030-10						
	(Ту	pe TH)				
Dim	Min	Max	Тур			
Α	0.70	0.80	0.75			
A1		0.05	0.02			
A3	0.18	0.25	0.20			
b	0.18	0.30	0.25			
D	2.90	3.10	3.00			
D2	2.40	2.60	2.50			
е		0.50BS	SC			
e1		2.00BS	SC			
Е	2.90	3.10	3.00			
E2	1.45	1.65	1.55			
h	0.20	0.30	0.25			
L	0.30	0.50	0.40			
All	Dimen	sions i	n mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



W-DEN3030-10	(Type TH)
W-DFN3030-10	(туретп)

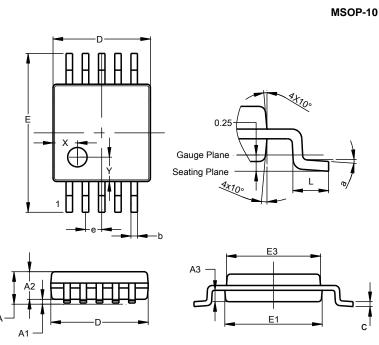
Dimensions	Value (in mm)
С	0.500
Х	0.300
X1	2.300
X2	2.600
Y	0.600
Y1	3.300
Y2	1.650

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

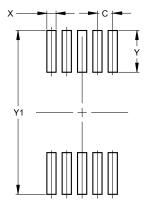


	MSC	OP-10	
Dim	Min	Max	Тур
Α	-	1.10	-
A1	0.05	0.15	0.10
A2	0.75	0.95	0.86
A3	0.29	0.49	0.39
b	0.17	0.27	0.20
C	0.08	0.23	0.15
D	2.95	3.05	3.00
e	-	-	0.50
Е	4.80	5.00	4.90
E1	2.95	3.05	3.00
E3	2.85	3.05	2.95
L	0.40	0.80	0.60
Х			0.750
Y			0.750
а	0°	8°	4°
All D	imens	sions i	n mm

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

MSOP-10



Dimensions	Value (in mm)
С	0.50
Х	0.30
Y	1.35
Y1	5.30

Note: For high-voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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